Revision History :

Revision 1.0 (Jul. 4, 2007)
- Original

PSRAM 16-Mbit (1M x 16) Pseudo Static RAM

Features

- Wide voltage range: 2.2V–3.6V
- Access Time: 70 ns
- Ultra-low active power— Typical active current: 3 mA @ f = 1 MHz— Typical active current: 18 mA @ f = fmax
- Ultra low standby power
- Automatic power-down when deselected
- CMOS for optimum speed/power
- Deep Sleep Mode
- Offered in a Lead-Free 48-ball BGA package
- Operating Temperature: –40°C to +85°C

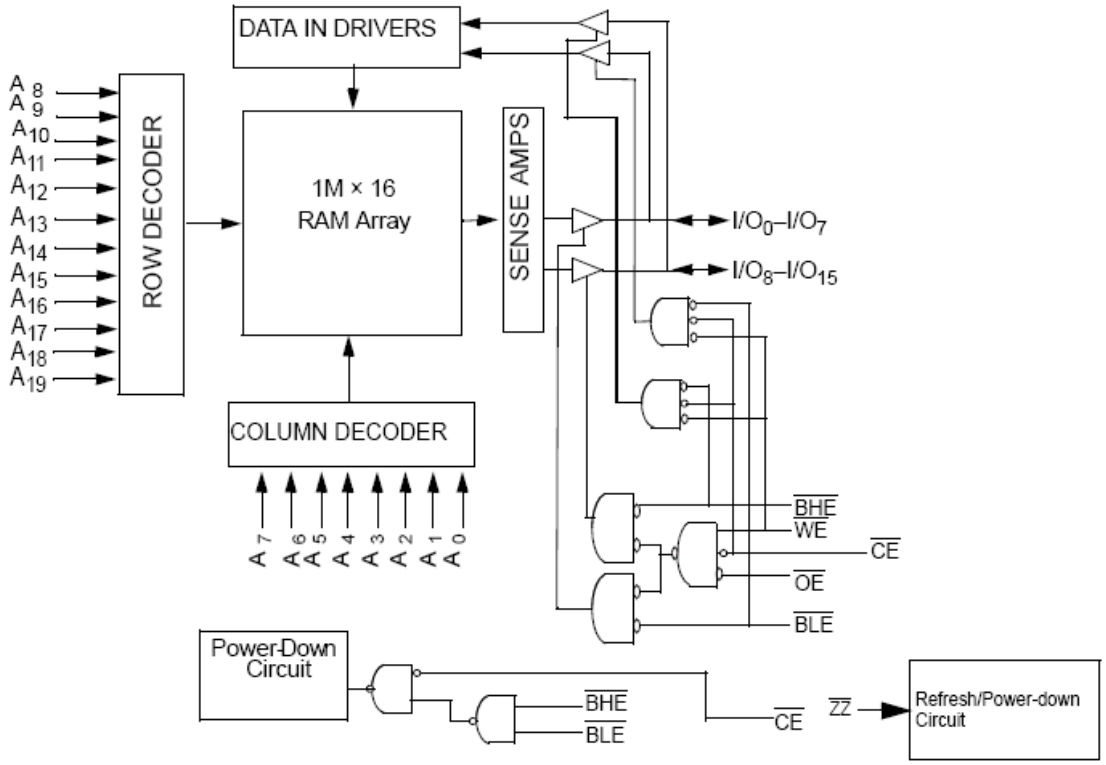
Functional Description[1]

The M24L16161ZA is a high-performance CMOS Pseudo Static RAM organized as 1M words by 16 bits that supports an asynchronous memory interface. This device features advanced circuit design to provide ultra-low active current. This is ideal for portable applications such as cellular telephones. The device can be put into standby mode when deselected ($\overline{OE}$ HIGH or both $\overline{BHE}$ and $\overline{BLE}$ are HIGH). The input/output pins (I/O_0 through I/O_{15}) are placed in a high-impedance state when: deselected ($\overline{OE}$ HIGH), outputs are disabled ($\overline{OE}$ HIGH), both Byte High Enable and Byte Low Enable are disabled ($\overline{BHE}$, $\overline{BLE}$ HIGH), or during a write operation ($\overline{CE}$ LOW and $\overline{WE}$ LOW).

To write to the device, take Chip Enable ($\overline{CE}$ LOW) and Write Enable ($\overline{WE}$) input LOW. If Byte Low Enable (BLE) is LOW, then data from I/O pins (I/O_0 through I/O_7), is written into the location specified on the address pins (A_0 through A_{19}). If Byte High Enable ($\overline{BHE}$) is LOW, then data from I/O pins (I/O_8 through I/O_{15}) is written into the location specified on the address pins (A_0 through A_{19}).

To read from the device, take Chip Enables ($\overline{CE}$ LOW) and Output Enable ($\overline{OE}$) LOW while forcing the Write Enable ($\overline{WE}$) HIGH. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from the memory location specified by the address pins will appear on I/O_0 to I/O_7. If Byte High Enable ($\overline{BHE}$) is LOW, then data from memory will appear on I/O_8 to I/O_{15}. Refer to the Truth Table for a complete description of read and write modes. To enable Deep Sleep Mode, drive $\overline{ZZ}$ LOW. See the Truth Table for a complete description of Read, Write, and Deep Sleep mode.

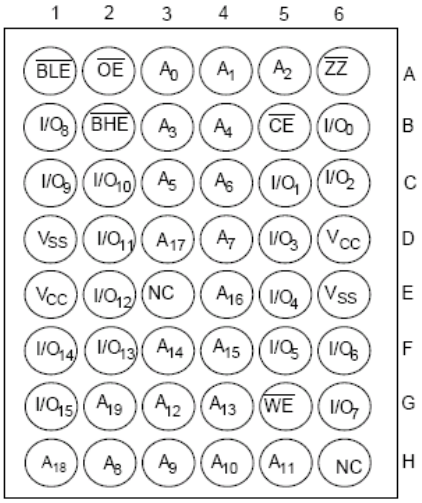
Logic Block Diagram



Pin Configuration[2, 3]

48-ball VFBGA

Top View



Product Portfolio Product

Product	V_{CC} Range (V)			Speed(ns)	Power Dissipation					
					Operating I_{CC}(mA)				Standby I_{SB2}(μA)	
					f = 1MHz		f = fmax			
	Min.	Typ.[4]	Max		.Typ.[4]	Max.	.Typ.[4]	Max	.Typ. [4]	Max
M24L16161ZA	2.2	3.0	3.6	70	3	5	18	25	55	70

Low-Power Modes

At power-up, all four sections of the die are activated and thePSRAM enters into its default state of full memory size andrefresh space. This device provides three different Low-Power Modes.

1.Reduced Memory Size Operation
2.Partial Array Refresh
3.Deep Sleep Mode
4.Temperature Controlled Refresh

Reduced Memory Size Operation

In this mode, the 16-Mb PSRAM can be operated as a 12-Mbit,8-Mbit, and 4-Mbit memory block. Refer to “Variable Address Space Register (VAR)” on page4 for the protocol to turn on/off sections of the memory. The device remains in RMS mode until changes to the Variable Address Space register are made to revert back to a complete 16-Mbit PSRAM.

Partial Array Refresh

The Partial Array Refresh mode allows customers to turn off sections of the memory block in Standby mode (with $\overline{ZZ}$ tied LOW) to reduce standby current. In this mode the PSRAM will only refresh certain portions of the memory in Standby Mode, as configured by the user through the settings in the Variable Address Register.

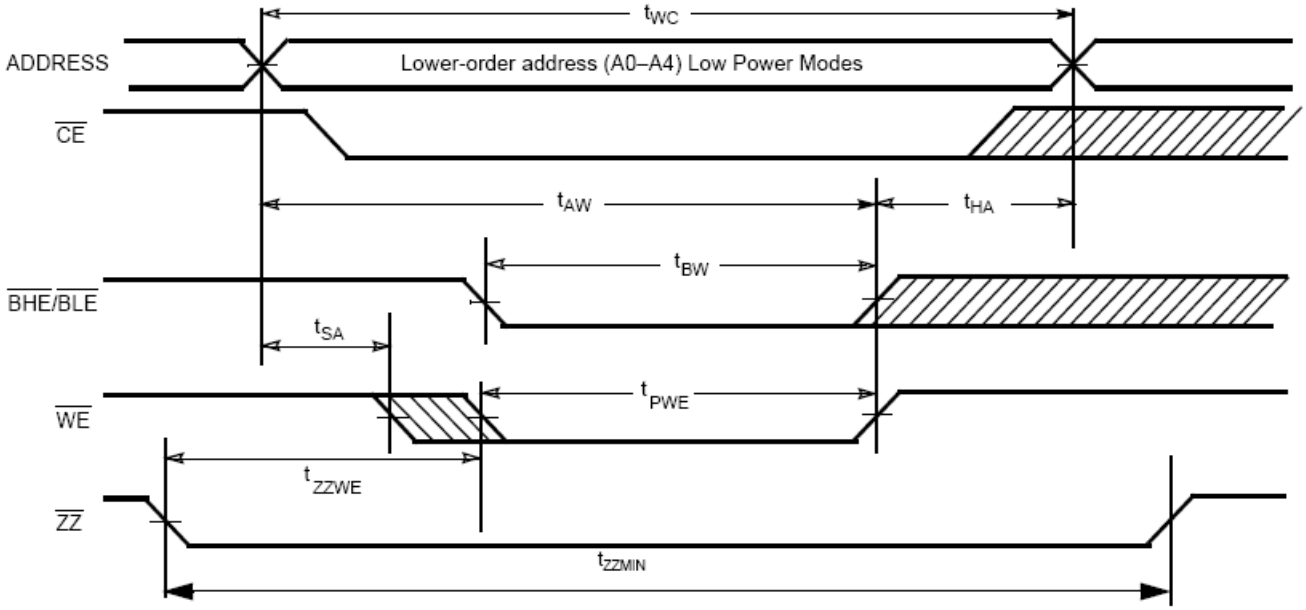
Once $\overline{ZZ}$ returns HIGH in this mode, the PSRAM goes back to operating in full address refresh. Refer to “Variable Address Space Register (VAR)” on page4 for the protocol to turn off sections of the memory in Standby mode. If the VAR register is not updated after power-up, the PSRAM will be in its default state. In the default state the whole memory array will be refreshed in Standby Mode. The 16-Mbit is divided into four 4-Mbit sections allowing certain sections to be active (i.e., refreshed).

Deep Sleep Mode

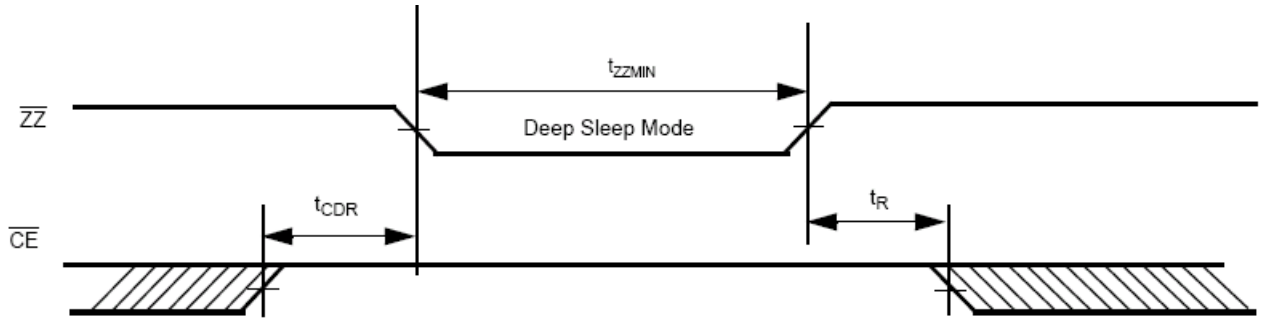
In this mode, the data integrity in the PSRAM is not guaranteed. This mode can be used to lower the power consumption of the PSRAM in an application. This mode can be enabled and disabled through VAR similar to the RMS and PAR mode. Deep Sleep Mode is activated by driving $\overline{ZZ}$ LOW. The device stays in the deep sleep mode until $\overline{ZZ}$ is driven HIGH.

Notes:
2. Ball H6 and E3 can be used to upgrade to a 32M and a 64M density respectively.
3. NC “no connect” - not connected internally to the die.
4. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = $V_{CC\ (typ)}$ and T_A = 25°C. Tested initially and after any design changes that may affect the parameter.

Variable Address Mode Register (VAR) Update[5, 6]



Deep Sleep Mode—Entry/Exit[7]



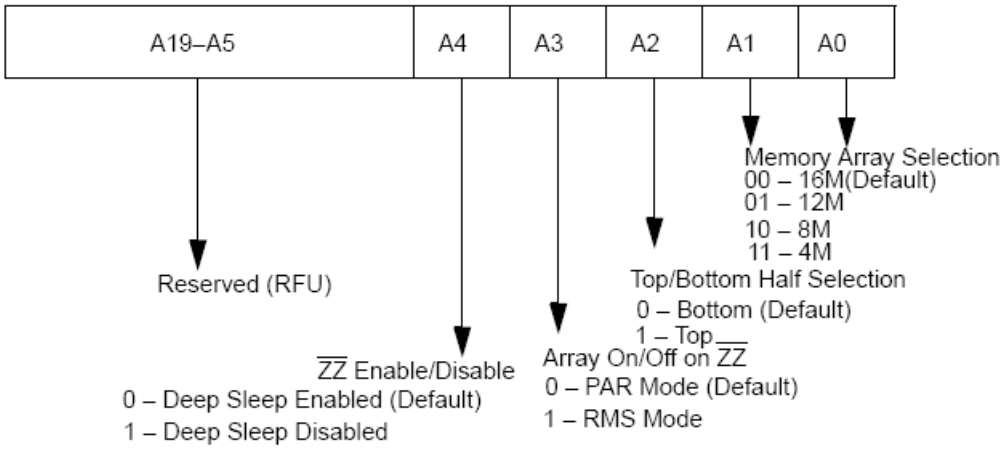
VAR Update and Deep Sleep Mode Timing[5, 6]

Parameter	Description	Min.	Max.	Unit
t_{ZZWE}	$\overline{ZZ}$ LOW to Write Start		1	µs
t_{CDR}	Chip deselect to $\overline{ZZ}$ LOW	0		ns
t_R[7]	Operation Recovery Time (Deep Sleep Mode only)	200		µs
t_{ZZMIN}	Deep Sleep Mode Time	8		µs

Notes:

5. $\overline{OE}$ and the data pins are in a don't care state while the device is in variable address mode.
6. All other timing parameters are as shown in the data sheets.
7. t_R applies only in the deep sleep mode.

Variable Address Space Register (VAR)

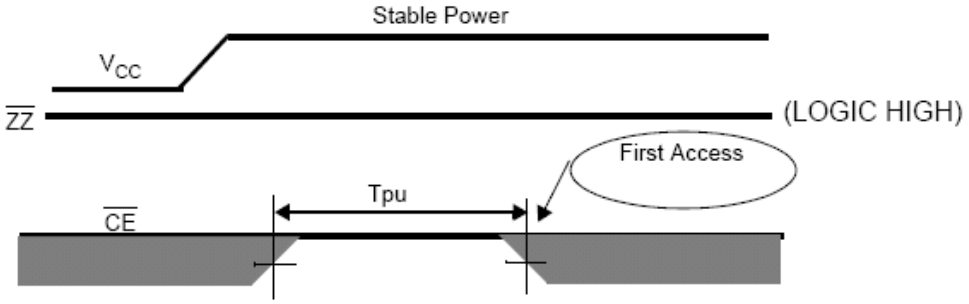


Variable Address Space—Address Patterns

Partial Array Refresh Mode (A3=0, A4=1)					
A2	**A1, A0**	**Refresh Section**	**Address**	**Size**	**Density**
0	1 1	1/4th of the array	00000h - 3FFFFh (A19 = A18 = 0)	256K x 16	4M
0	1 0	1/2th of the array	00000h - 7FFFFh (A19 = 0)	512K x 16	8M
0	0 1	3/4th of the array	00000h - BFFFFh (A19:A18 not equal to 11)	768K x 16	12M
1	1 1	1/4th of the array	C0000h - FFFFFh (A19 = A18 = 1)	256K x 16	4M
1	1 0	1/2th of the array	80000h - FFFFFh (A19 = 1)	512K x 16	8M
1	0 1	3/4th of the array	40000h - FFFFFh (A19:A18 not equal to 00)	786K x 16	12M
Reduced Memory Size Mode (A3=1, A4=1)					
0	1 1	1/4th of the array	00000h - 3FFFFh (A19 = A18= 0)	256K x 16	4M
0	1 0	1/2th of the array	00000h - 7FFFFh (A19 = 0)	512K x 16	8M
0	0 1	3/4th of the array	00000h - BFFFFh (A19:A18 not equal to 1 1)	768K x 16	12M
0	0 0	Full array	00000h - FFFFFh (Default)	1M x 16	16M
1	1 1	1/4th of the array	C0000h - FFFFFh (A19 = A18 = 1)	256K x 16	4M
1	1 0	1/2th of the array	80000h - FFFFFh (A19 = 1)	512K x 16	8M
1	0 1	3/4th of the array	40000h - FFFFFh (A19:A18 not equal to 00)	768K x 16	12M
1	0 0	Full array	00000h - FFFFFh (Default)	1M x 16	16M

Power-up Characteristics

The initialization sequence is shown in the figure below. Chip Select ($\overline{CE}$) should be HIGH for at least 200 μs after VCC has reached a stable value. No access must be attempted during this period of 200 μs. $\overline{ZZ}$ is high (H) for the duration of power-up.



Parameter	Description	Min.	Max.	Unit
T_{PU}	Chip Enable Low After Stable V_{CC}	200		μs

Maximum Ratings

(Above which the useful life may be impaired. For user guide-lines, not tested.)Storage Temperature .....–65°C to +150°C
Ambient Temperature with Power Applied.....–55°C to +125°C
Supply Voltage to Ground Potential.....–0.3V to V_{CCMAX} + 0.3V
DC Voltage Applied to Outputs in High Z State[8, 9, 10].....–0.3V to V_{CCMAX} + 0.3V
DC Input Voltage[8, 9, 10].....–0.3V to V_{CCMAX} + 0.3V
Output Current into Outputs (LOW).....20 mA
Static Discharge Voltage..... > 2001V (per MIL-STD-883, Method 3015)Latch-Up Current.....> 200 mA

Operating Range

Range	Ambient Temperature (T_A)	V_{CC}
Industrial	−40°C to +85°C	2.2V to 3.6V

DC Electrical Characteristics (Over the Operating Range) [8, 9, 10]

Parameter	Description	Test Conditions		-70			Unit
				Min.	Typ.[4]	Max.	
V_{CC}	Supply Voltage			2.2	3.0	3.6	V
V_{OH}	Output HIGH Voltage	I_{OH} = −0.1 mA V_{CC} = 2.2V to 3.6V		V_{CC}-0.2			V
V_{OL}	Output LOW Voltage	I_{OL} = 0.1 mA, V_{CC} = 2.2V to 3.6V				0.2	V
V_{IH}	Input HIGH Voltage	V_{CC} = 2.2V to 3.6V		0.8* V_{CC}		V_{CC}+0.3V	V
V_{IL}	Input LOW Voltage	V_{CC} = 2.2V to 3.6V		-0.3		0.2* V_{CC}	V
I_{IX}	Input Leakage Current	GND ≤ V_{IN} < V_{CC}		-1		+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_{OUT} ≤ V_{CC}		-1		+1	µA
I_{CC}	V_{CC} Operating Supply Current	f = f_{MAX} = 1/t_{RC}	V_{CC}= V_{CCmax} I_{OUT} = 0mA CMOS levels		18	25	mA
		f = 1 MHz			3	5	
I_{SB1}	Automatic $\overline{CE}$ Power-Down Current —CMOS Inputs	$\overline{CE}$ > V_{CC} − 0.2V, V_{IN} > V_{CC} − 0.2V, V_{IN} < 0.2V, f = f_{MAX} (Address and Data Only), f = 0 ($\overline{OE}$, $\overline{WE}$, $\overline{BHE}$ and $\overline{BLE}$), V_{CC}=3.60V, $\overline{ZZ}$ ≥ V_{CC} – 0.2V			55	70	µA
I_{SB2}	Automatic CE Power-Down Current —CMOS Inputs	$\overline{CE}$ > V_{CC}−0.2V, V_{IN} > V_{CC} − 0.2V or V_{IN} < 0.2V, f = 0, V_{CC} = V_{CCMAX}, $\overline{ZZ}$ ≥ V_{CC} – 0.2V			55	70	µA
I_{ZZ}	Deep Sleep Current	V_{CC} = V_{CCMAX}, $\overline{ZZ}$ < 0.2V, $\overline{CE}$ = HIGH or $\overline{BHE}$ and $\overline{BLE}$ = HIGH				10	µA

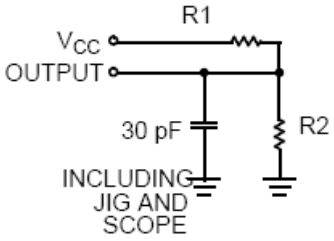
Capacitance[11]

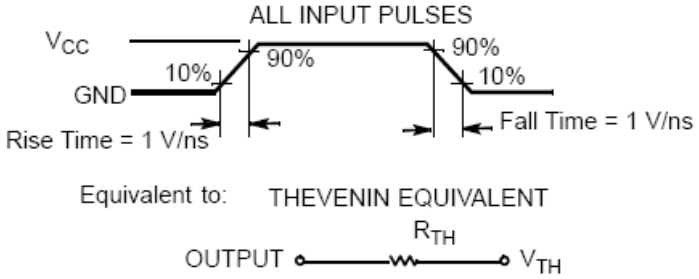
Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz V_{CC} = $V_{CC(typ)}$	8	pF

Notes:
8. $V_{IL(MIN)}$ = –0.5V for pulse durations less than 20 ns.
9. $V_{IH(Max)}$ = V_{CC} + 0.5V for pulse durations less than 20 ns.
10. Overshoot and undershoot specifications are characterized and are not 100% tested.
11. Tested initially and after any design or process changes that may affect these parameters..

Thermal Resistance[11]

Parameter	Description	Test Conditions	VFBGA	Unit
Θ_{JA}	Thermal Resistance (Junction to Ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedence, per EIA/JESD51.	56	˚C/W
Θ_{JC}	Thermal Resistance (Junction to Case)		11	˚C/W





Parameters	3.0V V_{CC}	Unit
R1	26000	Ω
R2	26000	Ω
R_{TH}	13000	Ω
V_{TH}	1.50	V

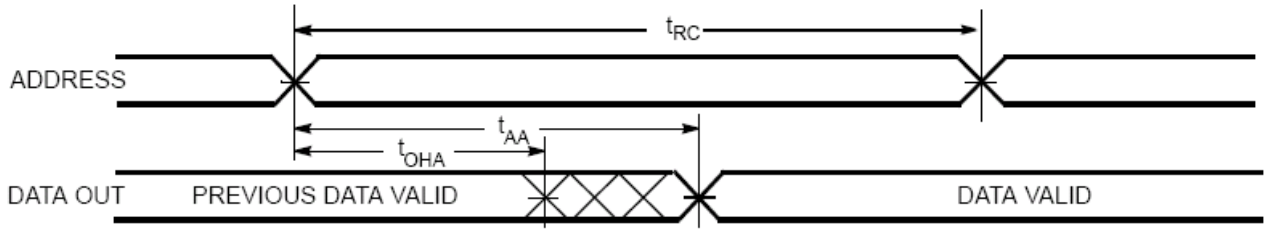
Switching Characteristics Over the Operating Range [12, 13, 14, 15, 18]

Parameter	Description	-70		Unit
		Min.	Max.	
Read Cycle				
t_{RC}[17]	Read Cycle Time	70	40000	ns
t_{CD}	Chip Deselect Time $\overline{CE}$, $\overline{BLE}$ / $\overline{BHE}$ High Pulse Time	15		ns
t_{AA}	Address to Data Valid		70	ns
t_{OHA}	Data Hold from Address Change	5		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		70	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid		35	ns
t_{LZOE}	$\overline{OE}$ LOW to Low Z[13, 14, 16]	5		ns
t_{HZOE}	$\overline{OE}$ HIGH to High Z[13, 14, 16]		25	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z[13, 14, 16]	10		ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z[13, 14, 16]		25	ns
t_{DBE}	$\overline{BLE}$ / $\overline{BHE}$ LOW to Data Valid		70	ns
t_{LZBE}	$\overline{BLE}$ / $\overline{BHE}$ LOW to Low Z[13, 14, 16]	5		ns
t_{HZBE}	$\overline{BLE}$ / $\overline{BHE}$ HIGH to High Z[13, 14, 16]		25	ns
Write Cycle[15]				
t_{WC}	Write Cycle Time	70	40000	ns
t_{SCE}	$\overline{CE}$ LOW to Write End	60		ns
t_{AW}	Address Set-Up to Write End	60		ns
t_{CD}	Chip Deselect Time $\overline{CE}$, $\overline{BLE}$ / $\overline{BHE}$ High Pulse Time	15		ns
t_{HA}	Address Hold from Write End	0		ns
t_{SA}	Address Set-Up to Write Start	0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	50		ns
t_{BW}	$\overline{BLE}$ / $\overline{BHE}$ LOW to Write End	60		ns
t_{SD}	Data Set-Up to Write End	25		ns
t_{HD}	Data Hold from Write End	0		ns
t_{HZWE}	$\overline{WE}$ LOW to High-Z[13, 14, 16]		25	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low-Z[13, 14, 16]	10		ns

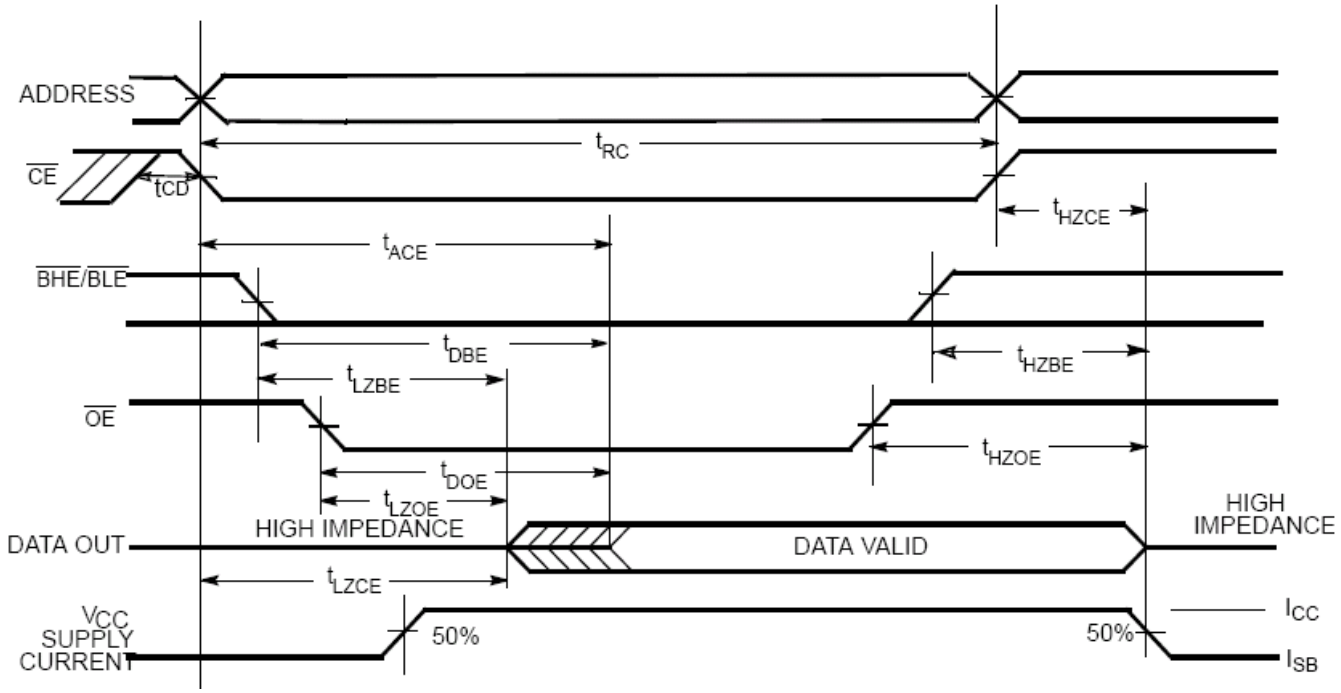
Notes:

12. Test conditions for all parameters other than tri-state parameters assume signal transition time of 1 ns/V, timing reference levels of V_{CC}/2, input pulse levels of 0V to V_{CC}, and output loading of the specified I_{OL}/I_{OH} as shown in the "AC Test Loads and Waveforms" section.
13. At any given temperature and voltage conditions t_{HZCE} is less than t_{LZCE}, t_{HZBE} is less than t_{LZBE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device. All low-Z parameters will be measured with a load capacitance of 30 pF (3V).
14. t_{HZOE}, t_{HZCE}, t_{HZBE}, and t_{HZWE} transitions are measured when the outputs enter a high-impedance state.
15. The internal Write time of the memory is defined by the overlap of $\overline{WE}$, $\overline{CE}$ = V_{IL}, $\overline{BHE}$ and/or $\overline{BLE}$ = V_{IL}. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input set-up and hold timing should be referenced to the edge of the signal that terminates the write.
16. High-Z and Low-Z parameters are characterized and are not 100% tested.
17. If invalid address signals shorter than min. t_{RC} are continuously repeated for 40 μs, the device needs a normal read timing (t_{RC}) or needs to enter standby state at least once in every 40 μs.18.In order to achieve 70-ns performance, the read access must be $\overline{CE}$ controlled. That is, the addresses must be stable prior to $\overline{CE}$ going active.

Switching Waveforms
Read Cycle 1 (Address Transition Controlled)[20, 21]

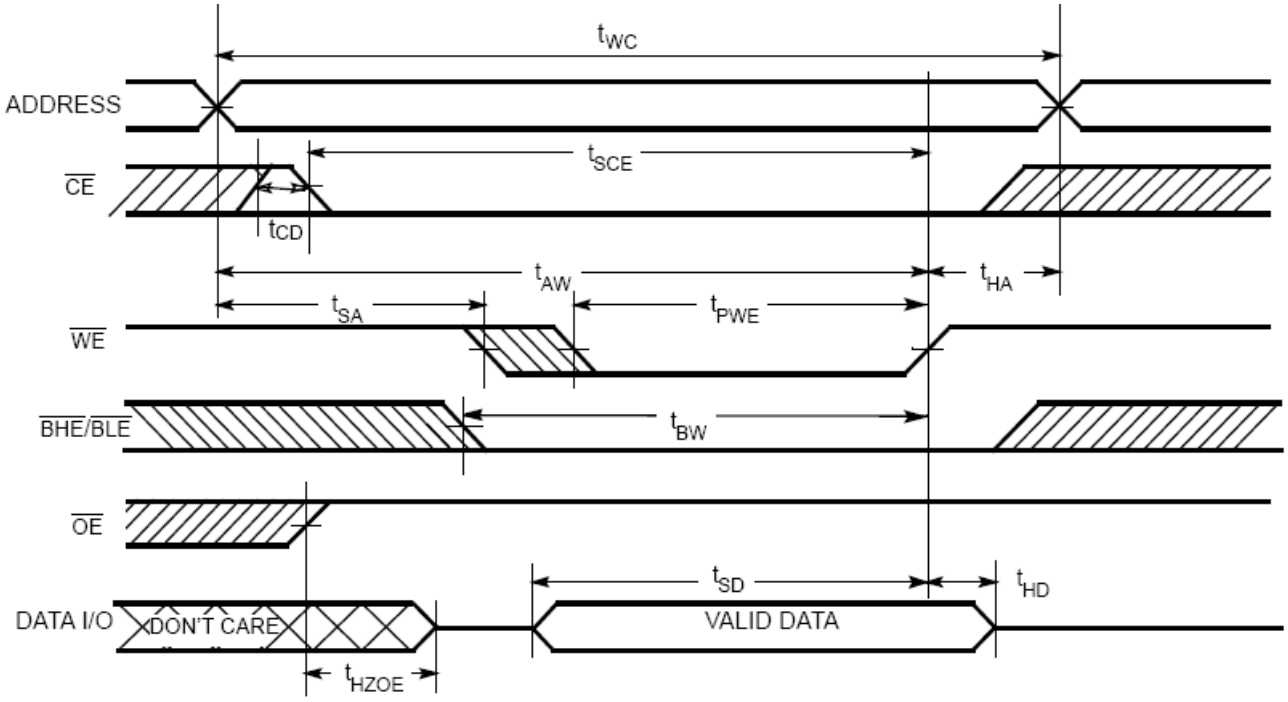


Read Cycle 2 ($\overline{OE}$ Controlled) [19, 21]



Notes:
19. Whenever $\overline{CE}$, $\overline{BHE}$ / $\overline{BLE}$ are taken inactive, they must remain inactive for a minimum of 15 ns.
20. Device is continuously selected. $\overline{OE}$, $\overline{CE}$ = V_{IL}.
21. $\overline{WE}$ is HIGH for Read Cycle.

Switching Waveforms (continued)



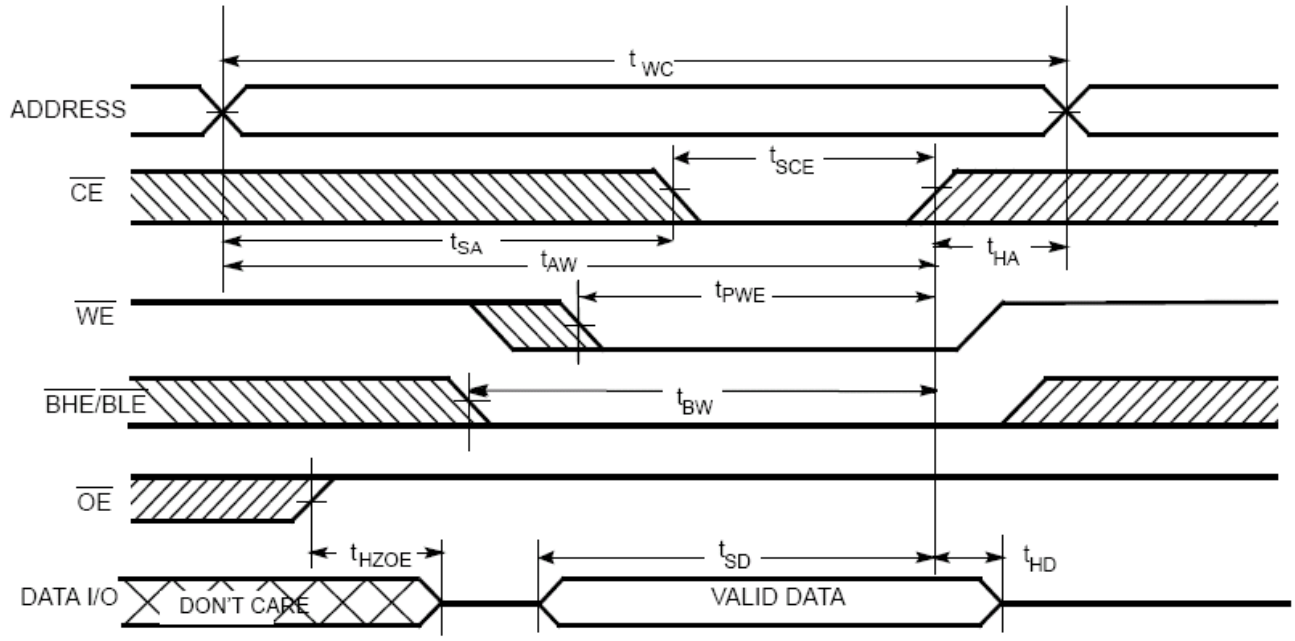
Notes:

22.Data I/O is high-Impedance if $\overline{OE}$ > V_{IH}.

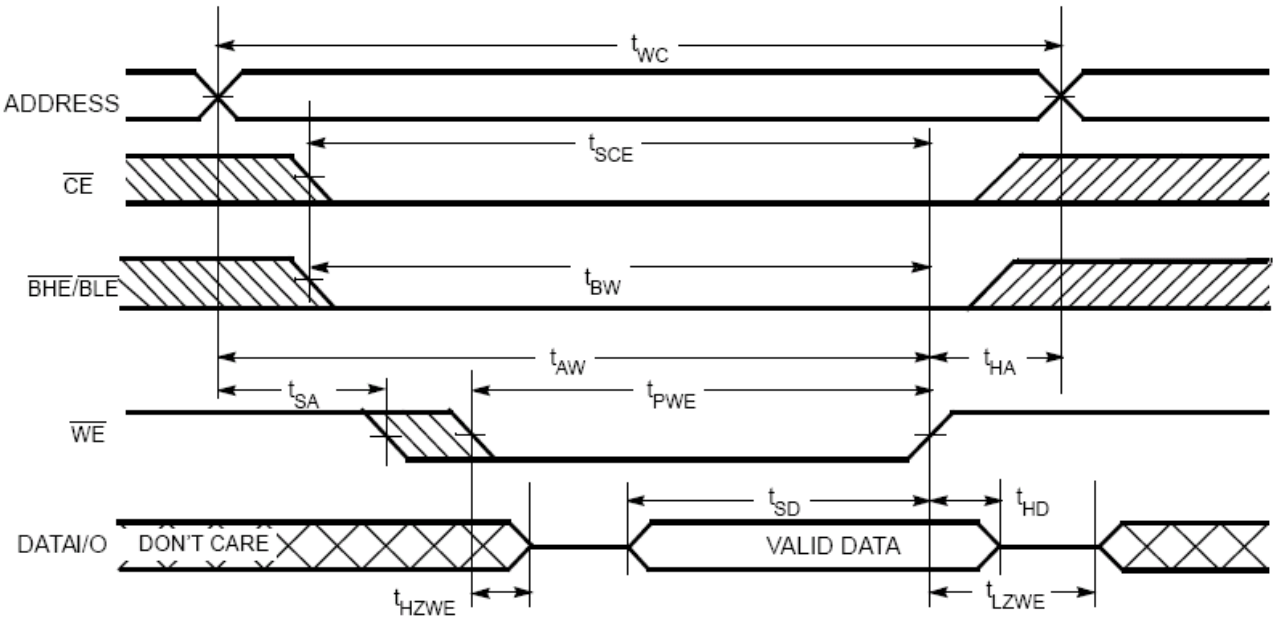
23.During the DON'T CARE period in the DATA I/O waveform, the I/Os are in output state and input signals should not be applied.

Switching Waveforms (continued)

Write Cycle 2 ($\overline{CE}$ Controlled) [15, 16, 19, 22, 23]

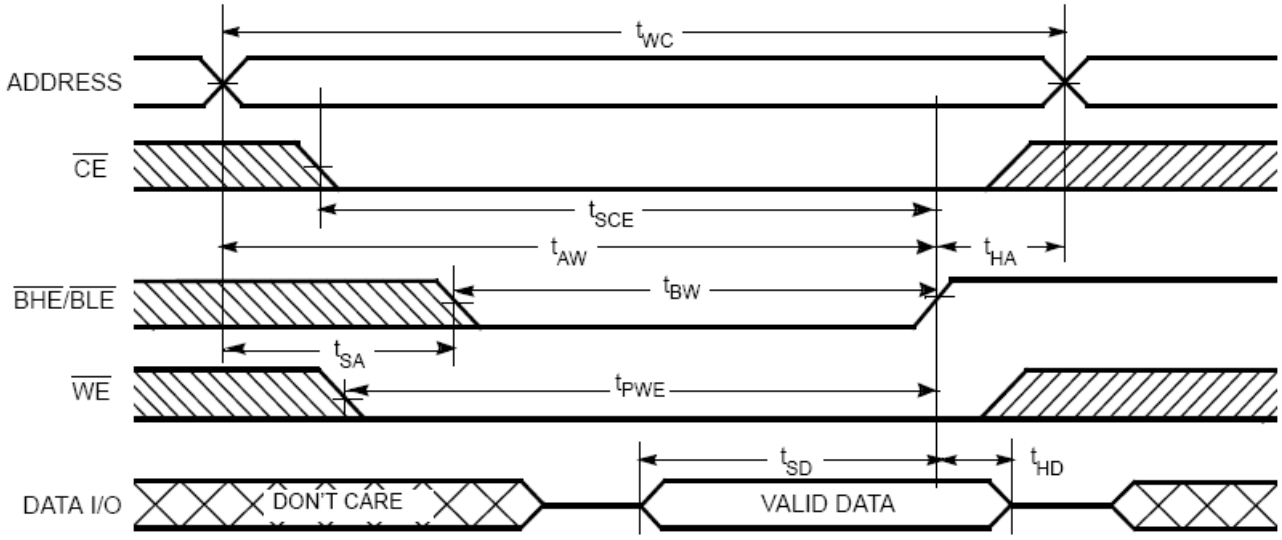


Write Cycle 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)[19, 23]



Switching Waveforms (continued)

Write Cycle 4 ($\overline{BHE}$/$\overline{BLE}$ Controlled, $\overline{OE}$ LOW)[15, 19, 22, 23]



Truth Table[24, 25]

$\overline{ZZ}$	$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	$\overline{BHE}$	$\overline{BLE}$	Inputs/Outputs	Mode	Power
H	H	X	X	X	X	High Z	Deselect/Power-Down	Standby (I_{SB})
H	X	X	X	H	H	High Z	Deselect/Power-Down	Standby (I_{SB})
H	L	X	X	H	H	High Z	Deselect/Power-Down	Standby (I_{SB})
H	L	H	L	L	L	Data Out (I/O_0–I/O_{15})	Read	Active (I_{CC})
H	L	H	L	H	L	Data Out (I/O_0–I/O_7); (I/O_8–I/O_{15}) in High Z	Read	Active (I_{CC})
H	L	H	L	L	H	Data Out (I/O_8–I/O_{15}); (I/O_0–I/O_7) in High Z	Read	Active (I_{CC})
H	L	H	H	L	L	High Z	Output Disabled	Active (I_{CC})
H	L	H	H	H	L	High Z	Output Disabled	Active (I_{CC})
H	L	H	H	L	H	High Z	Output Disabled	Active (I_{CC})
H	L	L	X	L	L	Data In (I/O_0–I/O_{15})	Write (Upper Byte and Lower Byte)	Active (I_{CC})
L	L	L	X	H	L	Data In (I/O_0–I/O_7); (I/O_8–I/O_{15}) in High Z	Write (Lower Byte Only)	Active (I_{CC})
L	L	L	X	L	H	Data Out (I/O_8–I/O_{15}); (I/O_0–I/O_7) in High Z	Write (Upper Byte Only)	Active (I_{CC})
L	L	L	X	L	L	Data In (A_0–A_4)	Write (Variable Address Mode Register)	Active (I_{CC})
L	H	X	X	X	X	High Z	Deep Power-down/PAR	Deep Sleep (I_{ZZ})/Standb

Notes:

24.H = Logic HIGH, L = Logic LOW, X = Don't Care.

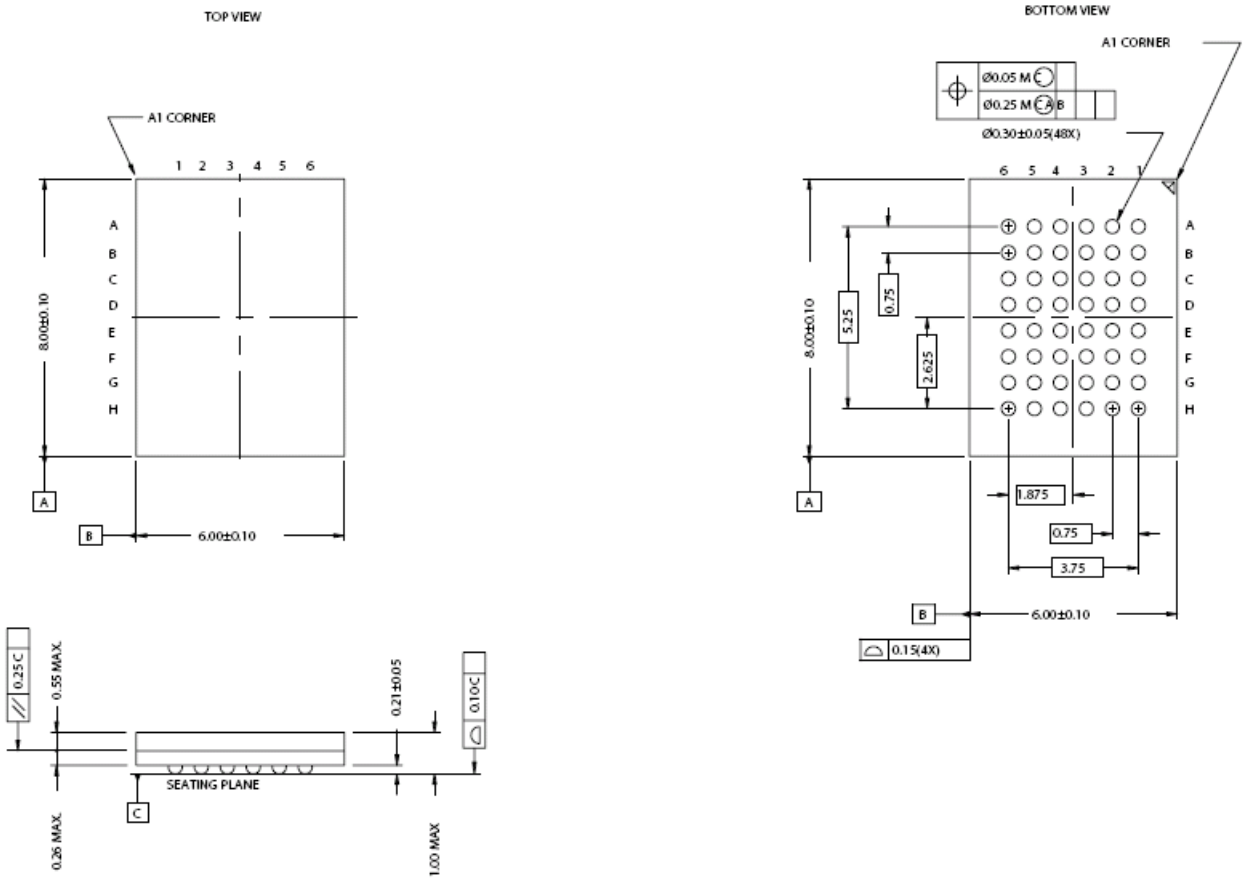
25.During $\overline{ZZ}$ = L and CE = H, Mode depends on how the VAR is set up either in PAR or Deep Sleep Modes.

Ordering Information

Speed (ns)	Ordering Code	Package Type	Operating Range
70	M24L16161ZA -70BIG	48-ball Very Fine Pitch BGA (6 x 8 x 1 mm) (Pb-Free)	Industrial

Package Diagrams

48-Lead VFBGA (6 x 8 x 1 mm)



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